

Title (en)

Arrangement for the supply of a molten copper alloy

Title (de)

Anordnung zum Abgiessen einer aus einer Kupferlegierung bestehenden Giessschmelze

Title (fr)

Dispositif pour couler un alliage fondu de cuivre

Publication

EP 1240958 A3 20030102 (DE)

Application

EP 02005162 A 20020308

Priority

DE 10112621 A 20010314

Abstract (en)

[origin: EP1240958A2] Assembly for pouring a molten copper alloy metal (3) has a smelting furnace (1) which tilts around a horizontal swing axis (2) with a pouring tube (4). The molten metal is poured under a protective gas atmosphere (9) at the casting end (5) of a pouring spout (6) and the outlet end of the pouring spout of an ingot mold. A hood (7) shrouds the molten metal against the atmosphere, and the entry for the pouring spout at the hood has a seal (8) with a swing movement.

IPC 1-7

B22D 11/103; **B22D 11/106**

IPC 8 full level

B22D 11/04 (2006.01); **B22D 11/10** (2006.01); **B22D 11/00** (2006.01); **B22D 11/103** (2006.01); **B22D 11/106** (2006.01); **B22D 21/00** (2006.01); **B22D 23/00** (2006.01); **B22D 35/04** (2006.01); **F27D 3/14** (2006.01)

CPC (source: EP KR US)

B22D 11/10 (2013.01 - KR); **B22D 11/103** (2013.01 - EP US); **B22D 11/106** (2013.01 - EP US)

Citation (search report)

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- [Y] EP 0697577 A1 19960221 - NIPPON MINING CO [JP], et al
- [YD] EP 0259772 A2 19880316 - MITSUBISHI METAL CORP [JP]
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CN102847924A

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

EP 1240958 A2 20020918; **EP 1240958 A3 20030102**; CN 1382545 A 20021204; DE 10112621 A1 20020919; HU 0200966 D0 20020529; HU P0200966 A2 20020928; HU P0200966 A3 20030228; JP 2002283042 A 20021002; KR 100864465 B1 20081022; KR 20020073299 A 20020923; PL 352768 A1 20020923; TW 531458 B 20030511; US 2002130449 A1 20020919; US 6602461 B2 20030805

DOCDB simple family (application)

EP 02005162 A 20020308; CN 02107523 A 20020314; DE 10112621 A 20010314; HU P0200966 A 20020313; JP 2002067479 A 20020312; KR 20020013537 A 20020313; PL 35276802 A 20020313; TW 91104246 A 20020307; US 9819902 A 20020314